



100% Material Declaration Data Sheet TQ176

PK170 (v1.2) October 5, 2006

Material Declaration Data Sheet

Average Weight: 1.776259 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.02752	1.55%
	Silicon	7440-21-3	100.00		0.02752	
Die Attach Material					0.003709	0.21%
	anhydride	Trade Secret	7.50		0.000278175	
	Silver	7440-22-4	77.50		0.002874475	
	Epoxy resin	Trade Secret	15.00		0.00055635	
Mold Compound					1.465	82.48%
	Epoxy Resin (EP)	Trade Secret	7.00		0.10255	
	Phenolic Resin	Trade Secret	5.00		0.07325	
	Carbon Black	1333-86-4	0.30		0.004395	
	Silica	60676-86-0	87.70		1.284805	
Leadframe					0.2601	14.64%
	Copper	7440-50-8	94.3		0.2452743	
	Magnesium	7439-95-4	0.30		0.0007803	
	Nickel	7440-02-0	1.2		0.0031212	
	Silicon	7440-21-3	4.2		0.0109242	
Bond Wire					0.00393	0.22%
	Gold	7440-57-5	100.00		0.00393	
Ext. Plating					0.016	0.90%
	Tin	7440-31-5	85.00		0.0136	
	Lead	7439-92-1	15.00		0.0024	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/23/06	1.0	Initial release.
7/05/06	1.1	100% Material Declaration.
10/5/06	1.2	Updated component descriptions.